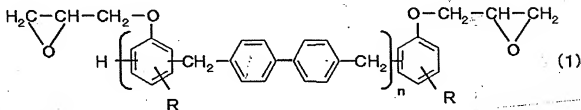


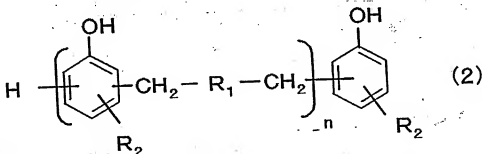
Amendments to the Specification

On page 3, replace lines 3-16 with the following:

This invention provides a resin composition for encapsulating a semiconductor chip comprising: an epoxy resin (A) represented by general formula (1):



wherein R represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average; a phenol resin (B) represented by general formula (2):

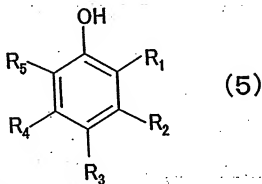


wherein R₁ represents phenylene or biphenylene; R₂ represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average; an inorganic filler (C); a curing accelerator (D); a silane coupling agent (E); and Compound (F) containing two and more hydroxyl groups ~~combined with each of~~ on adjacent carbon atoms comprising an aromatic ring.

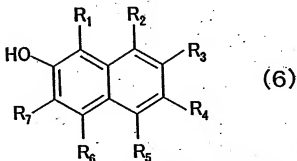
On page 13, please replace the paragraph beginning on line 4 to page 14, line 2, with the following:

Compound (F) containing two and more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring may contain optionally a substituent other than the hydroxyl groups.

Compound (F) may be a monocyclic compound represented by general formula (5):



wherein one of R₁ and R₅ is hydroxyl and the other is hydrogen, hydroxyl or a substituent other than hydroxyl; and R₂, R₃ and R₄ are hydrogen, hydroxyl or a substituent other than hydroxyl; or a polycyclic compound represented by general formula (6):



wherein one of R_1 and R_7 is hydroxyl and the other is hydrogen, hydroxyl or a substituent other than ~~hydroxyl~~hydroxyl; and R_2 , R_3 , R_4 , R_5 and R_6 are hydrogen, hydroxyl or a substituent other than hydroxyl.

Please replace Table 1 on page 21 with the following table:

TABLE 1

[illegible]